

With the two error outputs the TLE4729G signals malfunction of the device. Setting the control inputs low resets the error flag and by reactivating the bridges one by one the location of the error can be found.

### **Pin Configuration**

(top view)

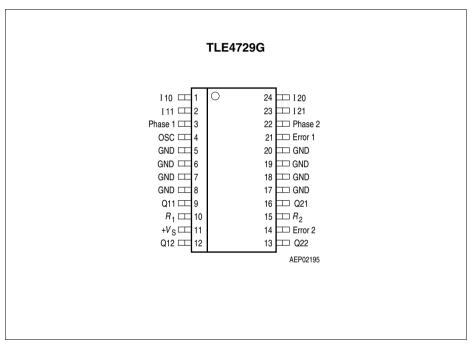


Figure 1



## **Pin Definitions and Functions**

Pin	Function									
1, 2, 23, 24	Digital control particular phase	-	the magnitude of the current of the							
	$I_{\text{set}} = 450 \text{ mA}$	with $R_{\rm sense}$ = 1 $\Omega$								
	IX1 IX0									
	L L	L L 0 No current <sup>1)</sup>								
	L H	H 0.155 $\times I_{\text{set}}$ Hold								
	H L	$I_{set}$	Normal mode							
	н н	$1.55 \times I_{\text{set}}$	Accelerate							
	"No current" in b		rcuit and current consumption will sink below							
3	Input phase 1; controls the current through phase winding 1. On H-potential the phase current flows from Q11 to Q12, on L-potential in the reverse direction.									
5 8, 17 20	Ground; all pins are connected at leadframe internally.									
4	<b>Oscillator;</b> works at approx. 25 kHz if this pin is wired to ground across 2.2 nF.									
10	Resistor R <sub>1</sub> for	sensing the current	in phase 1.							
9, 12	Push-pull outp	outs Q11, Q12 for ph	nase 1 with integrated free-wheeling							
11		ic capacitor of at lea	s close as possible to the IC, with a last 47 $\mu\text{F}$ in parallel with a ceramic							
14	_	signals with "low" tl tputs or over-tempe	ne errors: short circuit to ground of rature.							
13, 16	Push-pull outp	outs Q22, Q21 for ph	nase 2 with integrated free-wheeling							
15	Resistor $R_2$ for	sensing the current	in phase 2.							
21			e errors: open load or short circuit to t circuit of the load or over-							
22	· ·	phase current flows	flow through phase winding 2. On from Q21 to Q22, on L-potential in							



## **Block Diagram**

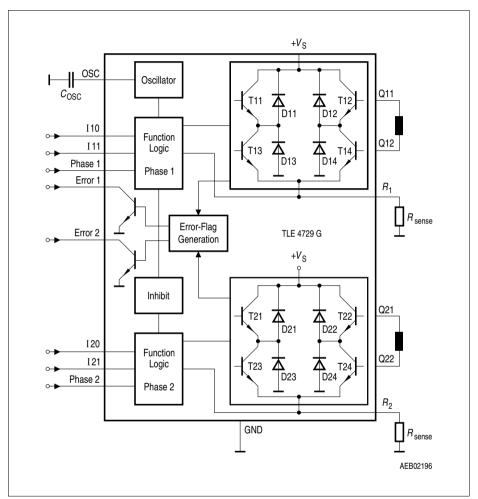


Figure 2



## **Absolute Maximum Ratings**

 $T_{\rm j}$  = - 40 to 150 °C

Parameter	Symbol Limit		Values	Unit	Remarks
		min.	max.		
Supply voltage	$V_{S}$	- 0.3	45	٧	_
Error outputs	$V_{Err}$	- 0.3	45	٧	_
	$I_{Err}$	_	3	mA	_
Output current	$I_{Q}$	<b>– 1</b>	1	Α	_
Ground current	$I_{GND}$	-2	_	Α	_
Logic inputs	$V_{IXX}$	<b>– 15</b>	15	٧	IXX; Phase 1, 2
Oscillator voltage	$V_{OSC}$	- 0.3	6	٧	_
$R_1$ , $R_2$ input voltage	$V_{RX}$	- 0.3	5	V	-
Junction temperature	$T_{j}$	- 40	150	°C	
Storage temperature	$T_{stg}$	- 50	150	°C	-
Thermal resistances Junction-ambient Junction-ambient (soldered on a 35 $\mu$ m thick 20 cm <sup>2</sup> PC board copper area)	R <sub>th ja</sub> R <sub>th ja</sub>		75 50	K/W K/W	-
Junction-case	$R_{thjc}$	_	15	K/W	Measured on pin 5

## **Operating Range**

Supply voltage	$V_{S}$	5	16	V	_
Case temperature	$T_{\mathbb{C}}$	- 40	110	°C	Measured on pin 5 $P_{\text{diss}} = 2 \text{ W}$
Output current	$I_{Q}$	- 800	800	mA	_
Logic inputs	$V_{IXX}$	<b>-</b> 5	+ 6	٧	IXX; Phase 1, 2
Error outputs	$V_{Err}$	_	25	٧	_
	$I_{Err}$	0	1	mΑ	_



### **Characteristics**

 $V_{\rm S}$  = 6 to 16 V;  $T_{\rm i}$  = - 40 to 130 °C

Symbol	Limit Values			Unit	Test Condition
	min.	typ.	max.		
	Symbol		,		

### **Current Consumption**

•						
From + V <sub>S</sub>	$I_{S}$	_	_	50	μΑ	IXX = L; $V_S$ = 12 V;
						<i>T</i> <sub>j</sub> ≤ 85 °C
From + $V_{S}$	$I_{S}$	20	30	50	mA	$I_{Q1, 2} = 0 \text{ A}$

### Oscillator

Output charging current	$I_{OSC}$	90	120	150	μΑ	_
Charging threshold	$V_{OSCL}$	8.0	1.3	1.9	V	_
Discharging threshold	$V_{OSCH}$	1.7	2.3	2.9	V	_
Frequency	$f_{OSC}$	18	24	30	kHz	$C_{\rm OSC}$ = 2.2 nF

## Phase Current ( $V_{\rm S}$ = 9 ... 16 V)

Mode "no current"	$I_{Q}$	_	0	_	mA	IX0 = L; IX1 = L
Voltage threshold of						
current Comparator at						
$R_{\rm sense}$ in mode:						
Hold	$V_{ch}$	40	70	100	mV	IX0 = H; $IX1 = L$
Setpoint	$V_{cs}$	410	450	510	mV	IX0 = L; IX1 = H
Accelerate	$V_{ca}$	630	700	800	mV	IX0 = H; IX1 = H

## Logic Inputs (Phase X)

• • •						
Threshold	$V_{l}$	1.2	1.7	2.2	٧	_
Hysteresis	$V_{IHv}$	_	200	_	mV	_
L-input current	$I_{IL}$	<b>– 10</b>	<b>– 1</b>	1	μΑ	$V_{\rm I}$ = 1.2 V
L-input current	$I_{IL}$	- 100	- 20	<b>-</b> 5	μΑ	$V_{I} = 0 V$
H-input current	$I_{IH}$	<b>– 1</b>	0	10	μΑ	$V_{I} = 5 V$

## Logic Inputs (IX1; IX0)

Threshold	$V_{I}$	8.0	1.7	2.2	V	_
Hysteresis	$V_{IHv}$	_	200	_	mV	_
L-input current	$I_{IL}$	- 100	_	+ 5	μΑ	$V_{I} = 0 V$
H-input current	$I_{IH}$	5	20	50	μΑ	$V_{I} = 5 V$



## Characteristics (cont'd)

 $V_{\rm S}$  = 6 to 16 V;  $T_{\rm i}$  = - 40 to 130 °C

Parameter	Symbol	Lir	Limit Values			Test Condition
		min.	typ.	max.		

## **Error Outputs**

Saturation voltage	$V_{ErrSat}$	50	200	500	mV	I <sub>Err</sub> = 1 mA
Leakage current	$I_{ErrL}$	_	_	10	μΑ	$V_{Err}$ = 25 V

### **Thermal Protection**

Olevstelesses	T	4.40	450	100	00	7 0 4
Shutdown	$I_{isd}$	140	150	160	°C	$I_{Q1, 2} = 0 \text{ A}$
Prealarm	$T_{\text{jpa}}$	120	130	140	°C	$V_{Err} = L$
Delta	$\Delta T_{i}$	10	20	30	K	$\Delta T_{\rm j} = T_{\rm jsd} - T_{\rm jpa}$
Hysteresis shutdown	$T_{isdhy}$	_	20	_	K	_
Hysteresis prealarm	$T_{\text{jpahy}}$	_	20	_	K	_

## Power Outputs Diode Transistor Sink Pair (D13, T13; D14, T14; D23, T23; D24, T24)

Saturation voltage	$V_{satl}$	0.1	0.3	0.5	٧	$I_{\rm O} = -0.45 \; {\rm A}$
Saturation voltage	$V_{satl}$	0.2	0.5	8.0	٧	$I_{Q} = -0.7 \text{ A}$
Reverse current	$I_{RI}$	500	1000	1500	μΑ	$V_{\rm S} = V_{\rm Q} = 40 \text{ V}$
Forward voltage	$V_{FI}$	0.6	0.9	1.2	V	$I_{\rm Q} = 0.45 \; {\rm A}$
Forward voltage	$V_{FI}$	0.7	1.0	1.3	V	$I_{\rm Q} = 0.7  {\rm A}$

## Diode Transistor Source Pair (T11, D11; T12, D12; T21, D21; T22, D22)

Saturation voltage	$V_{\sf satuC}$	0.6	1.0	1.2	V	$I_{\rm O} = 0.45  \text{A}$ ; charge
Saturation voltage	$V_{satuD}$	0.1	0.3	0.6	٧	$I_{\rm Q} = 0.45 \text{ A};$
						discharge
Saturation voltage	$V_{\sf satuC}$	0.7	1.2	1.5	٧	$I_{\rm O}$ = 0.7 A; charge
Saturation voltage	$V_{satuD}$	0.2	0.5	0.8	V	$I_{\rm O} = 0.7 \text{ A};$
						discharge
Reverse current	$I_{Ru}$	400	800	1200	μΑ	$V_{\rm S} = 40  \rm V,  V_{\rm Q} = 0  \rm V$
Forward voltage	$V_{Fu}$	0.7	1.0	1.3	V	$I_{\rm O} = -0.45  {\rm A}$
Forward voltage	$V_{Fu}$	8.0	1.1	1.4	V	$I_{\rm O} = -0.7  {\rm A}$
Diode leakage current	$I_{SL}$	0	3	10	mA	$I_{\rm F} = -0.7  {\rm A}$



## Characteristics (cont'd)

 $V_{\rm S}$  = 6 to 16 V;  $T_{\rm j}$  = – 40 to 130 °C

Parameter	Symbol	Limit Values			Unit	Test Condition
		min.	typ.	max.		
Error Output Timing						
Time Phase X to IXX	$t_{Pl}$	_	5	20	μS	_
Time IXX to Phase X	$t_{IP}$	_	12	100	μS	

45

15

30

3

1

100

50

80

10

5

μS

μS

μS

μS

μS

For details see next four pages.

Delay Phase X to Error 2

Delay Phase X to Error 1

Reset delay after Phase X

Delay IXX to Error 2

Reset delay after IXX

These parameters are not 100% tested in production, but guaranteed by design.

 $t_{\mathsf{PEsc}}$ 

 $t_{\mathsf{PEol}}$ 

 $t_{\mathsf{IEsc}}$ 

 $t_{\mathsf{RP}}$ 

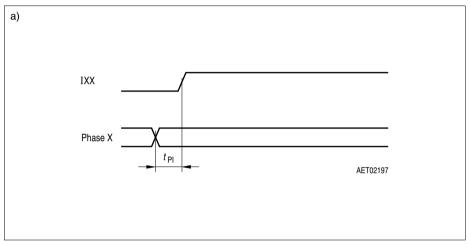
 $t_{\mathsf{RI}}$ 



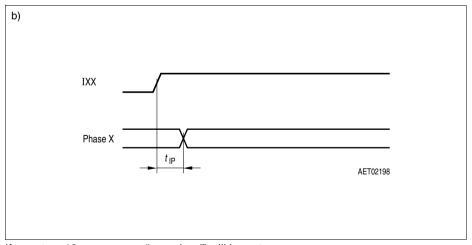
## **Diagrams**

Timing between IXX and Phase X to prevent setting the error flag Operating conditions:

+ 
$$V_{\rm S}$$
 = 14 V,  $T_{\rm i}$  = 25 °C,  $I_{\rm err}$  = 1 mA, load = 3.3 mH, 1  $\Omega$ 



If  $t_{Pl}$  < typ. 5 µs, an error "open load" will be set.

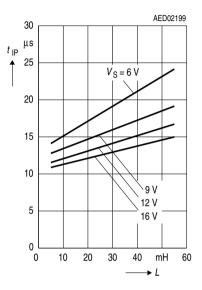


If  $t_{IP}$  < typ. 12  $\mu$ s, an error "open load" will be set.



This time strongly depends on +  $V_{\rm S}$  and inductivity of the load, see diagram below.

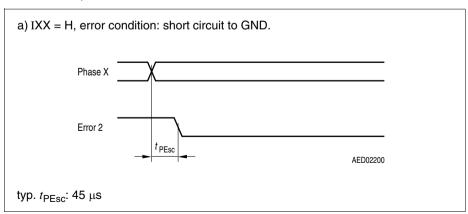
## Time $t_{\rm IP}$ vs. Load Inductivity



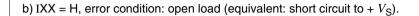
## **Propagation Delay of the Error Flag**

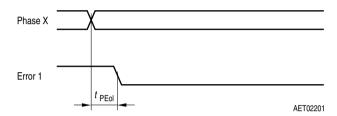
Operating conditions:

+ 
$$V_{\rm S}$$
 = 14 V,  $T_{\rm j}$  = 25 °C,  $I_{\rm err}$  = 1 mA, load = 3.3 mH, 1  $\Omega$ 

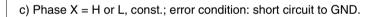


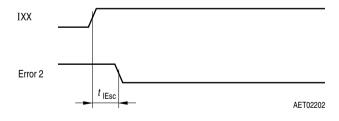






typ. t<sub>PEol</sub>: 15 μs



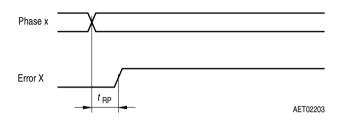


typ.  $t_{\mathsf{IEsc}}$ : 30  $\mu \mathsf{s}$ 

 $t_{\rm IEsc}$  is also measured under the condition: begin of short circuit to GND till error flag set.

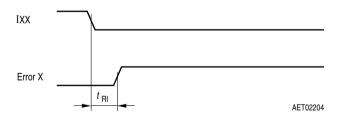


d) IXX = H, reset of error flag when error condition is not true.



typ. *t*<sub>RP</sub>: 3 μs

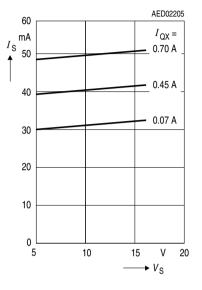
e) Phase X = H or L, const.; reset of error flag when error condition is not true.



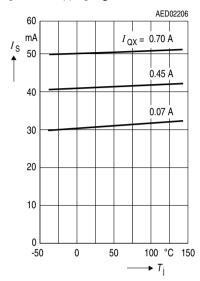
typ.  $t_{\text{BI}}$ : 1  $\mu$ s



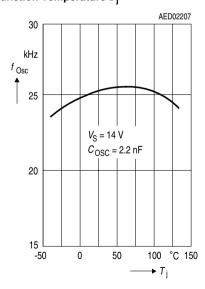
Quiescent Current  $I_{\rm S}$  vs. Supply Voltage  $V_{\rm S}$ ; bridges not chopping;  $T_{\rm i}$  = 25 °C



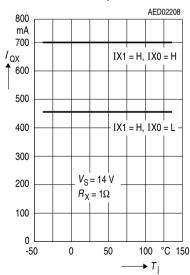
Quiesc. Current  $I_{\rm S}$  vs. Junct. Temp.  $T_{\rm j}$ ; bridges not chopping,  $V_{\rm S}$  = 14 V



# Oscillator Frequency $f_{\mathrm{Osc}}$ vs. Junction Temperature $T_{\mathrm{i}}$

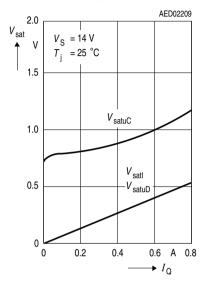


# Output Current $I_{\rm QX}$ vs. Junction Temperature $T_{\rm i}$

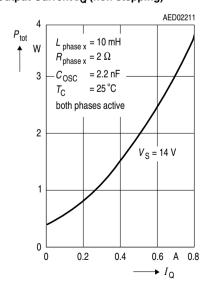




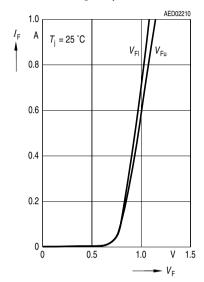
## Output Saturation Voltages $V_{\rm sat}$ vs. Output Current $I_{\rm Q}$



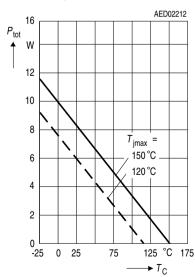
## Typical Power Dissipation $P_{\text{tot}}$ vs. Output Current $I_{\Omega}$ (non stepping)



## Forward Current $I_{\rm F}$ of Free-Wheeling Diodes vs. Forward Voltages $V_{\rm F}$

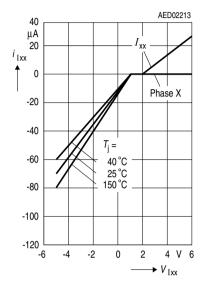


# Permissible Power Dissipation $P_{\mathrm{tot}}$ vs. Case Temp. $T_{\mathrm{C}}$ (measured at pin 5)

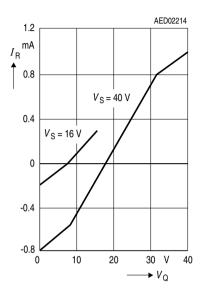




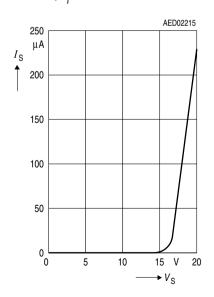
## Input Characteristics of $I_{\rm XX}$ , Phase X



### **Output Leakage Current**



# Quiescent Current $I_{\rm S}$ vs. Supply Voltage $V_{\rm S}$ ; inhibit mode; $T_{\rm j}$ = 25 °C





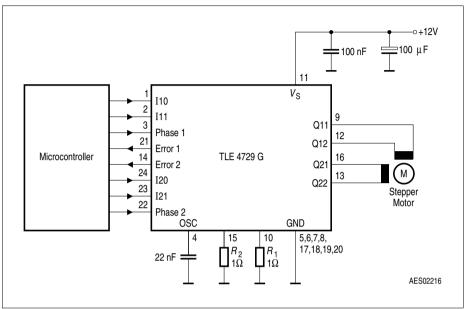


Figure 3 Application Circuit



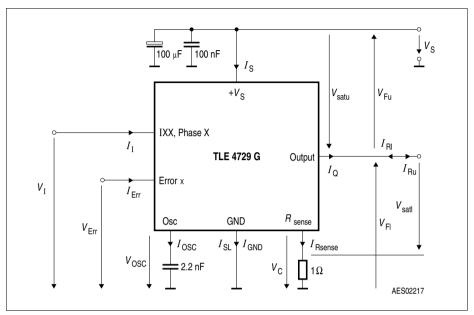


Figure 4 Test Circuit



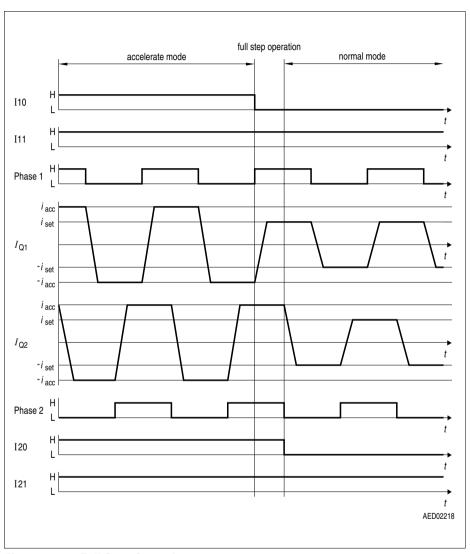


Figure 5 Full Step Operation



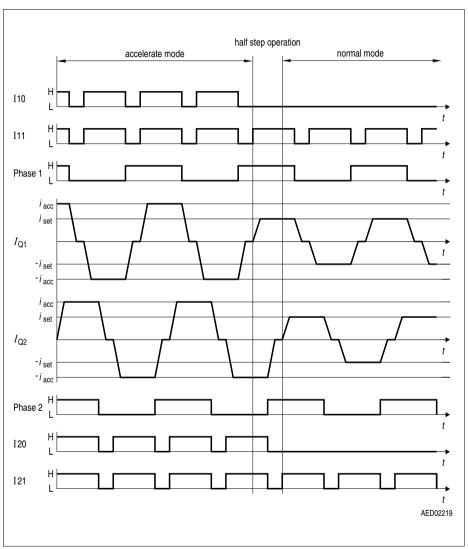


Figure 6 Half Step Operation



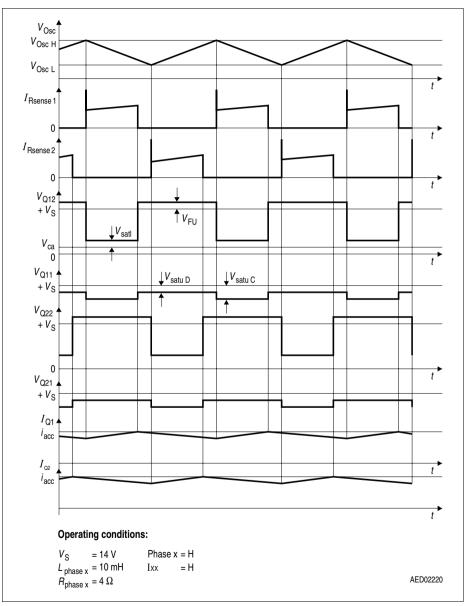


Figure 7 Current Control in Chop-Mode



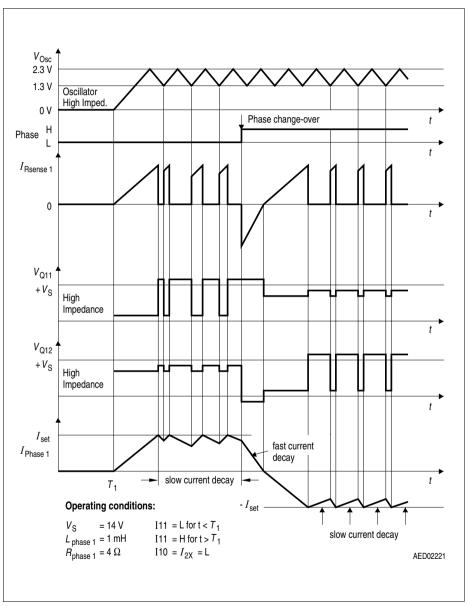


Figure 8 Phase Reversal and Inhibit



### Calculation of Power Dissipation

The total power dissipation  $P_{tot}$  is made up of

Saturation losses  $P_{\rm sat}$  (transistor saturation voltage and diode forward voltages),

Quiescent losses  $P_{\alpha}$  (quiescent current times supply voltage) and

Switching losses  $P_s$  (turn-ON / turn-OFF operations).

The following equations give the power dissipation for chopper operation without phase reversal.

This is the worst case, because full current flows for the entire time and switching losses occur in addition.

$$P_{\text{tot}} = 2 \times P_{\text{sat}} + P_{\text{q}} + 2 \times P_{\text{s}}$$
 where

$$\begin{aligned} P_{\text{sat}} & \cong I_{\text{N}} \left\{ V_{\text{SatI}} \times d + V_{\text{Fu}} \left( 1 - d \right) + V_{\text{satuC}} \times d + V_{\text{satuD}} \left( 1 - d \right) \right\} \\ P_{\text{q}} & = I_{\text{q}} \times V_{\text{S}} \end{aligned}$$

$$P_{\rm q} \cong \frac{V_{\rm S}}{T} \left\{ \frac{i_{\rm D} \times t_{\rm DON}}{2} + \frac{(i_{\rm D} + i_{\rm R}) \times t_{\rm ON}}{4} + \frac{I_{\rm N}}{2} (t_{\rm DOFF} + t_{\rm OFF}) \right\}$$

 $I_N$  = Nominal current (mean value)

 $I_{\alpha}$  = Quiescent current

 $i_D$  = Reverse current during turn-on delay

i<sub>B</sub> = Peak reverse current

 $t_{\rm p}$  = Conducting time of chopper transistor

 $t_{ON}$  = Turn-ON time

 $t_{OFF} = Turn-OFF time$ 

 $t_{DON} = Turn-ON delay$ 

 $t_{DOFF} = Turn-OFF delay$ 

T = Cycle duration

 $d = \text{Duty cycle } t_{\text{p}} / T$ 

 $V_{\text{satt}}$  = Saturation voltage of sink transistor (TX3, TX4)

 $V_{\text{satuC}}$ = Saturation voltage of source transistor (TX1, TX2) during charge cycle

 $V_{\text{satuD}}$  = Saturation voltage of source transistor (TX1, TX2) during discharge cycle

 $V_{\text{Fu}}$  = Forward voltage of free-wheeling diode (DX1, DX2)

 $V_{\rm S}$  = Supply voltage



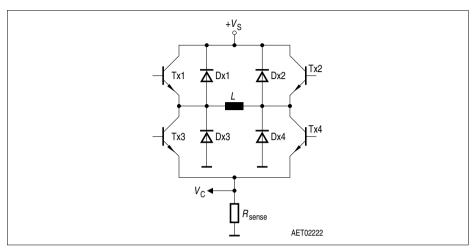


Figure 9

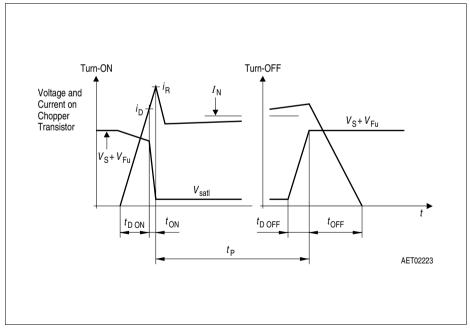


Figure 10 Voltage and Current on Chopper Transistor



### **Application Hints**

The TLE4729G is intended to drive both phases of a stepper motor. Special care has been taken to provide high efficiency, robustness and to minimize external components.

### **Power Supply**

The TLE4729G will work with supply voltages ranging from 5 V to 16 V at pin  $V_{\rm S}$ . Surges exceeding 16 V at  $V_{\rm S}$  wont harm the circuit up to 45 V, but whole function is not guaranteed. As soon as the voltage drops below approximately 16 V the TLE4729G works promptly again.

As the circuit operates with chopper regulation of the current, interference generation problems can arise in some applications. Therefore the power supply should be decoupled by a 0.1  $\mu$ F ceramic capacitor located near the package. Unstabilized supplies may even afford higher capacities.

### **Inhibit Mode**

In the case of low at all four current program inputs IXX the device will switch into inhibit condition; the current consumption is reduced to very low values.

When starting operation again, i.e. putting at least one IXX to high potential, the Error 1 output signals an open load error if the corresponding phase input is high. The error is reset by first recirculation in chop mode.

### **Current Sensing**

The current in the windings of the stepper motor is sensed by the voltage drop across  $R_{\rm sense}$ . Depending on the selected current internal comparators will turn off the sink transistor as soon as the voltage drop reaches certain thresholds (typical 0 V, 0.07 V, 0.45 V and 0.7 V). These thresholds are not affected by variations of  $V_{\rm S}$ . Consequently instabilized supplies will not affect the performance of the regulation. For precise current level it must be considered, that internal bounding wire (typ. 60 m $\Omega$ ) is a part of  $R_{\rm sense}$ .

Due to chopper control fast current rises (up to 10 A/ $\mu$ s) will occur at the sensing resistors. To prevent malfunction of the current sensing mechanism  $R_{\rm sense}$  should be pure ohmic. The resistors should be wired to GND as directly as possible. Capacitive loads such as long cables (with high wire to wire capacity) to the motor should be avoided for the same reason.

### Synchronizing Several Choppers

In some applications synchrone chopping of several stepper motor drivers may be desirable to reduce acoustic interference. This can be done by forcing the oscillator of the TLE4729G by a pulse generator overdriving the oscillator loading currents (approximately  $\pm$  120  $\mu A). In these applications low level should be between 0 V and 0.8 V while high level should between 3 V and 5 V.$ 



### Application Hints (cont'd)

### **Optimizing Noise Immunity**

Unused inputs should always be wired to proper voltage levels in order to obtain highest possible noise immunity.

To prevent crossconduction of the output stages the TLE4729G uses a special break before make timing of the power transistors. This timing circuit can be triggered by short glitches (some hundred nanoseconds) at the phase inputs causing the output stage to become high resistive during some microseconds. This will lead to a fast current decay during that time. To achieve maximum current accuracy such glitches at the phase inputs should be avoided by proper control signals.

To lower EMI a ceramic capacitor of max. 3 nF is advisable from each output to GND.

#### Thermal Shut Down

To protect the circuit against thermal destruction, thermal shut down has been implemented.

### **Error Monitoring**

The error outputs signal corresponding to the logic table the errors described below.

## Logic Table

Kind of Error		Error Output				
		Error 1	Error 2			
a)	No error	Н	Н			
b)	Short circuit to GND	Н	L			
c)	Open load <sup>1)</sup>	L	Н			
d)	b) and c) simultaneously	Н	L			
e)	Temperature prealarm	L	L			

<sup>1)</sup> Also possible: short circuit to +  $V_S$  or short circuit of the load.

**Over-Temperature** is implemented as pre-alarm; it appears approximately 20 K before thermal shut down. To detect an **open load**, the recirculation of the inductive load is watched. If there is no recirculation after a phase change-over, an internal error flipflop is set. Because in most kinds of **short circuits** there won't flow any current through the motor, there will be no recirculation after a phase change-over, and the error flipflop for open load will be set, too. Additionally an **open load error** is signaled after a phase change-over during hold mode.



Only in the case of a **short circuit to GND**, the most probably kind of a short circuit in automotive applications, the malfunction is signaled dominant (see d) in logic table) by a separate error flag. Simultaneously the output current is disabled after 30  $\mu$ s to prevent disturbances.

A phase change-over or putting both current control inputs of the affected bridge on low potential resets the error flipflop. Being a separate flipflop for every bridge, the error can be located in easy way.



### **Package Outlines**

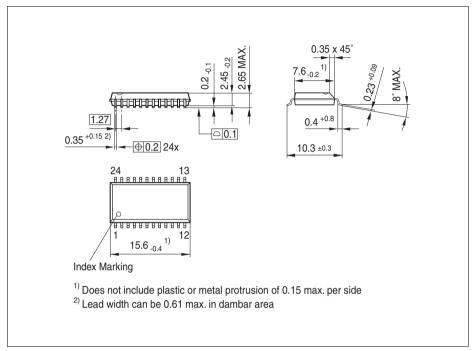


Figure 11 PG-DSO-24-16 (Plastic Green Dual Small Outline)

### **Green Product** (RoHS compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

You can find all of our packages, sorts of packing and others in our Infineon Internet Page "Products": http://www.infineon.com/products.

SMD = Surface Mounted Device

Dimensions in mm



## **Revision History**

Version	Date	Changes				
Rev. 1.1	2007-09-17	RoHS-compliant version of the TLE 4729 G				
		<ul> <li>All pages: Infineon logo updated</li> <li>Page 2: "added AEC qualified" and "RoHS" logo, "Green Product (RoHS compliant)" and "AEC qualified" statement added to feature list, package name changed to RoHS compliant versions, package picture updated, ordering code removed</li> <li>Page 27: Package name changed to RoHS compliant versions, "Green Product" description added</li> <li>added Revision History</li> <li>added Legal Disclaimer</li> </ul>				
Rev. 1.2	2008-03-18	Update Package suffix				



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#### Information

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (www.infineon.com).

#### Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.